

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/28/2022

Details for "BQ27411DRZT-G1A"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
BQ27411DRZT-G1A	NIPDAU	Level-2-260C-1 YEAR	TI PHILIPPINES CLARK A/T	DRZ 12	2.5x4x0.9	33

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Indium	7440-74-6	0.000001	0.001772	18	0.000003	0
Precious Metals	Gold	7440-57-5	0.056429	99.996456	999965	0.170782	1708
Precious Metals	Silver	7440-22-4	0.000001	0.001772	18	0.000003	0
Sub-Total			0.056431	100	1000000	0.170788	1708
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.430272	80	800000	1.302214	13022
Thermoplastics	Epoxy	85954-11-6	0.107568	20	200000	0.325553	3256
Sub-Total			0.53784	100	1000000	1.627767	16278
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	17.5536	97.52	975200	53.125792	531258
Copper and Its Alloys	Iron	7439-89-6	0.414	2.3	23000	1.252967	12530
Copper and Its Alloys	Phosphorus	7723-14-0	0.0054	0.03	300	0.016343	163
Zinc and Its Alloys	Zinc	7440-66-6	0.027	0.15	1500	0.081715	817
Sub-Total			18	100	1000000	54.476817	544768
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.513648	95.12	951200	1.55455	15546
Precious Metals	Gold	7440-57-5	0.004212	0.78	7800	0.012748	1274
Precious Metals	Palladium	7440-05-3	0.02214	4.1	41000	0.067006	670
Sub-Total			0.54	100	1000000	1.634305	16343
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.766842	88.000005	880000	32.585738	325857
Other Organic Materials	Chlorine	7782-50-5	0.000122	0.000997	10	0.000369	4
Other Plastics and Rubber	Carbon Black	1333-86-4	0.036705	0.299999	3000	0.111087	1111
Thermoplastics	Epoxy	85954-11-6	1.431378	11.698999	116990	4.332051	43321
Sub-Total			12.235047	100	1000000	37.029245	370292
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.67226	100	1000000	5.061078	50611
Sub-Total			1.67226	100	1000000	5.061078	50611
Total			33.041578			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.